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ICS8516I
LOW SKEW, 1-TO-16
DIFFERENTIAL-TO-LVDS CLOCK DISTRIBUTION CHIP

GENERAL DESCRIPTION

The ICS8516I is a low skew, high performance 1-to-16 Differential-to-LVDS Clock Distribution Chip and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS8516I CLK, nCLK pair can accept any differential input levels and translates them to 3.3V LVDS output levels. Utilizing Low Voltage Differential Signaling (LVDS), the ICS8516I provides a low power, low noise, point-to-point solution for distributing clock signals over controlled impedances of 100Ω.

Dual output enable inputs allow the ICS8516I to be used in a 1-to-16 or 1-to-8 input/output mode. Guaranteed output and part-to-part skew specifications make the ICS8516I ideal for those applications demanding well defined performance and repeatability.

FEATURES

- 16 Differential LVDS outputs

- CLK, nCLK pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, HCSL, SSTL

- Maximum output frequency: 700MHz

- Translates any differential input signal (LVPECL, LVHSTL, SSTL, DCM) to LVDS levels without external bias networks

- Translates any single-ended input signal to LVDS with resistor bias on nCLK input

- Multiple output enable inputs for disabling unused outputs in reduced fanout applications

- LVDS compatible

- Output skew: 65ps (maximum)

- Part-to-part skew: 550ps (maximum)

- Propagation delay: 2.4ns (maximum)

- 3.3V operating supply

- -40°C to 85°C ambient operating temperature

BLOCK DIAGRAM
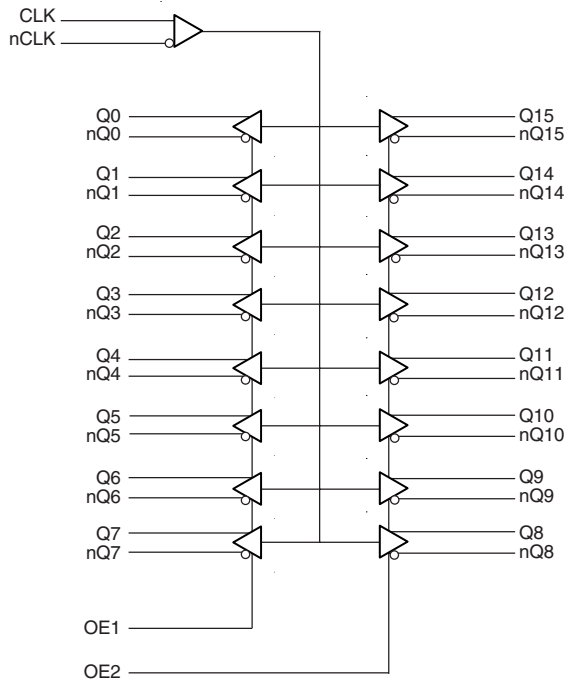
PIN ASSIGNMENT
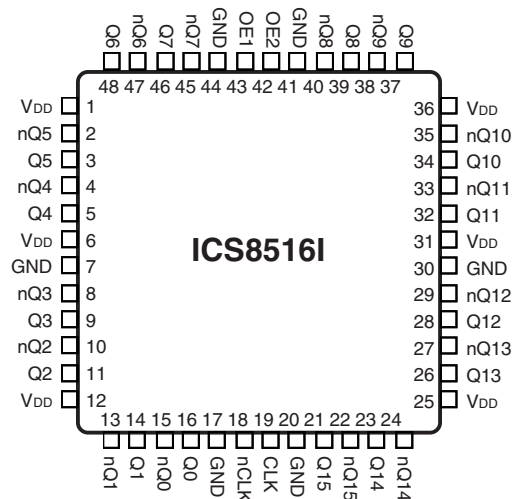
48-Lead LQFP
7mm x 7mm x 1.4mm body package
Y Package
Top View

TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1, 6, 12, 25, 31, 36	V_{DD}	Power		Positive supply pins.
2, 3	nQ5, Q5	Output		Differential output pair. LVDS interface levels.
4, 5	nQ4, Q4	Output		Differential output pair. LVDS interface levels.
7, 17, 20, 30, 41, 44	GND	Power		Power supply ground.
8, 9	nQ3, Q3	Output		Differential output pair. LVDS interface levels.
10, 11	nQ2, Q2	Output		Differential output pair. LVDS interface levels.
13, 14	nQ1, Q1	Output		Differential output pair. LVDS interface levels.
15, 16	nQ0, Q0	Output		Differential output pair. LVDS interface levels.
18	nCLK	Input	Pullup	Inverting differential clock input.
19	CLK	Input	Pulldown	Non-inverting differential clock input.
21, 22	Q15, nQ15	Output		Differential output pair. LVDS interface levels.
23, 24	Q14, nQ14	Output		Differential output pair. LVDS interface levels.
26, 27	Q13, nQ13	Output		Differential output pair. LVDS interface levels.
28, 29	Q12, nQ12	Output		Differential output pair. LVDS interface levels.
32, 33	Q11, nQ11	Output		Differential output pair. LVDS interface levels.
34, 35	Q10, nQ10	Output		Differential output pair. LVDS interface levels.
37, 38	Q9, nQ9	Output		Differential output pair. LVDS interface levels.
39, 40	Q8, nQ8	Output		Differential output pair. LVDS interface levels.
42, 43	OE2, OE1	Input	Pullup	Output enable. OE2 controls outputs Q8, nQ8 thru Q15, nQ15; OE1 controls outputs Q0, nQ0 thru Q7, nQ7. LVCMOS/LVTTL interface levels.
45, 46	nQ7, Q7	Output		Differential output pair. LVDS interface levels.
47, 48	nQ6, Q6	Output		Differential output pair. LVDS interface levels.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

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Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			4		pF
R_{PULLUP}	Input Pullup Resistor			51		KΩ
$R_{PULLDOWN}$	Input Pulldown Resistor			51		KΩ
C_{PD}	Power Dissipation Capacitance (per output)			4		pF

Table 3A. Control Input Function Table

Inputs		Outputs			
OE1	OE2	Q0:Q7	nQ0:nQ7	Q8:Q15	nQ8:nQ15
0	0	Hi Z	Hi Z	Hi Z	Hi Z
1	0	ACTIVE	ACTIVE	Hi Z	Hi Z
0	1	Hi Z	Hi Z	ACTIVE	ACTIVE
1	1	ACTIVE	ACTIVE	ACTIVE	ACTIVE

In the active mode, the state of the outputs are a function of the CLK and nCLK inputs as described in Table 3B.

Table 3B. Clock Input Function Table

Inputs		Outputs		Input to Output Mode	Polarity
CLK	nCLK	Q0:Q15	nQ0:nQ15		
0	1	LOW	HIGH	Differential to Differential	Non Inverting
1	0	HIGH	LOW	Differential to Differential	Non Inverting
0	Biased; NOTE 1	LOW	HIGH	Single Ended to Differential	Non Inverting
1	Biased; NOTE 1	HIGH	LOW	Single Ended to Differential	Non Inverting
Biased; NOTE 1	0	HIGH	LOW	Single Ended to Differential	Inverting
Biased; NOTE 1	1	LOW	HIGH	Single Ended to Differential	Inverting

NOTE 1: Please refer to the Application Information section, "Wiring the Differential Input to Accept Single Ended Levels".

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ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{DD}	4.6V
Inputs, V_I	-0.5V to V_{DD} + 0.5V
Outputs, I_O	
Continuous Current	10mA
Surge Current	15mA
Package Thermal Impedance, θ_{JA}	47.9°C/W (0 lfpm)
Storage Temperature, T_{STG}	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 4A. POWER SUPPLY DC CHARACTERISTICS, V_{DD} = 3.3V±5%, T_A = -40°C TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Positive Supply Voltage		3.135	3.3	3.465	V
I_{DD}	Static Power Supply Current	R_L = 100Ω			185	mA
		No Load			80	mA

TABLE 4B. LVCMOS/LVTTL DC CHARACTERISTICS, V_{DD} = 3.3V±5%, T_A = -40°C TO 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage	OE1, OE2		2		V_{DD} + 0.3	V
V_{IL}	Input Low Voltage	OE1, OE2		-0.3		0.8	V
I_{IH}	Input High Current	OE1, OE2	V_{DD} = V_{IN} = 3.465V			5	μA
I_{IL}	Input Low Current	OE1, OE2	V_{DD} = 3.465V, V_{IN} = 0V	-150			μA

TABLE 4C. DIFFERENTIAL DC CHARACTERISTICS, V_{DD} = 3.3V±5%, T_A = -40°C TO 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
I_{IH}	Input High Current	CLK	V_{IN} = V_{DD} = 3.465V			150	μA
		nCLK	V_{IN} = V_{DD} = 3.465V			5	μA
I_{IL}	Input Low Current	CLK	V_{DD} = 3.465V, V_{IN} = 0V	-5			μA
		nCLK	V_{DD} = 3.465V, V_{IN} = 0V	-150			μA
V_{PP}	Peak-to-Peak Voltage			0.15		1.3	V
V_{CMR}	Common Mode Input Voltage; NOTE 1, 2			GND + 0.5		V_{DD} - 0.85	V

NOTE 1: For single ended applications, the maximum input voltage for CLK, nCLK is V_{DD} + 0.3V.
NOTE 2: Common mode voltage is defined ast V_{IH}.

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TABLE 4D. LVDS DC CHARACTERISTICS, V_{DD} = 3.3V±5%, T_A = -40°C TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OD}	Differential Output Voltage		250	400	600	mV
ΔV_{OD}	V_{OD} Magnitude Change				50	mV
V_{OS}	Offset Voltage		1.125	1.4	1.6	V
ΔV_{OS}	V_{OS} Magnitude Change				50	mV
I_{OZ}	High Impedance Leakage Current		-10		+10	µA
I_{OFF}	Power Off Leakage		-1		+1	µA
I_{OSD}	Differential Output Short Circuit Current				-5.5	mA
I_{OS}/I_{OSB}	Output Short Circuit Current				-12	mA

TABLE 5. AC CHARACTERISTICS, V_{DD} = 3.3V±5%, T_A = -40°C TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency				700	MHz
t_{PD}	Propagation Delay; NOTE 1		1.6	2.0	2.4	ns
$t$sk(o)	Output Skew; NOTE 2, 4				65	ps
$t$sk(pp)	Part-to-Part Skew; NOTE 3, 4				550	ps
t_R/t_F	Output Rise/Fall Time	20% to 80%	50		600	ps
odc	Output Duty Cycle	$f \leq$ 600MHz	45		55	%
t_{PZL}, t_{PZH}	Output Enable Time; NOTE 5				5	ns
t_{PLZ}, t_{PHZ}	Output Disable Time; NOTE 5				5	ns

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.
NOTE 2: Defined as skew between outputs at the same supply voltages and with equal load conditions. Measured at the output differential cross points.
NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.
NOTE 5: These parameters are guaranteed by characterization. Not tested in production.
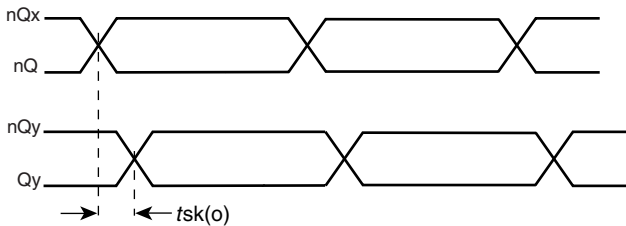
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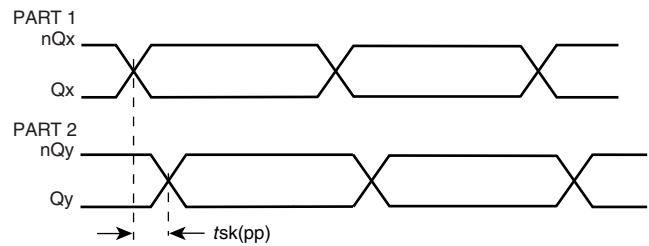DIFFERENTIAL-TO-LVDS CLOCK DISTRIBUTION CHIP

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PARAMETER MEASUREMENT INFORMATION

3.3V ± 5%

Z = 50Ω

Z = 50Ω

Power Supply
Float GND

LVDS

SCOPE

Qx

nQx

50Ω

50Ω
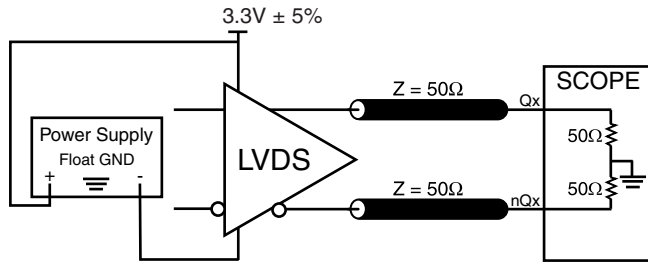
3.3V OUTPUT LOAD AC TEST CIRCUIT
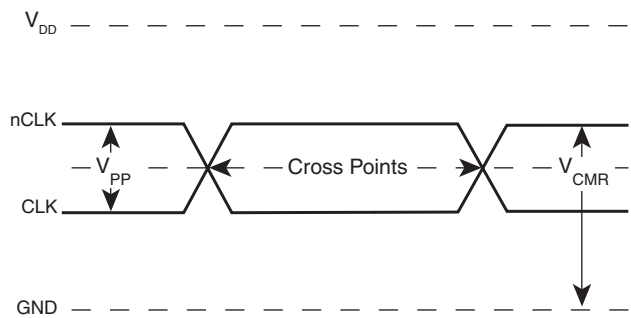
V_{DD}

nCLK

CLK

GND

V_{PP}

Cross Points

V_{CMR}

DIFFERENTIAL INPUT LEVEL

nQx

nQ

nQy

Qy

$t$sk(o)

OUTPUT SKEW

PART 1
nQx

Qx

PART 2
nQy

Qy

$t$sk(pp)

PART-TO-PART SKEW

nCLK

CLK

nQ0:nQ15

Q0:Q15

t_{PD}

PROPAGATION DELAY

80%

80%

V_{OD}

Clock
Outputs

20%

20%

t_R

t_F

OUTPUT RISE/FALL TIME

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$$odc = \frac{t_{PW}}{t_{PERIOD}}$$
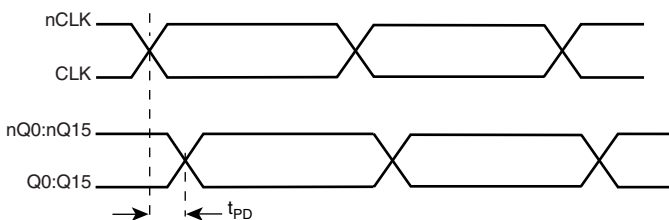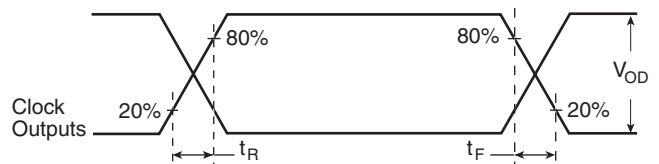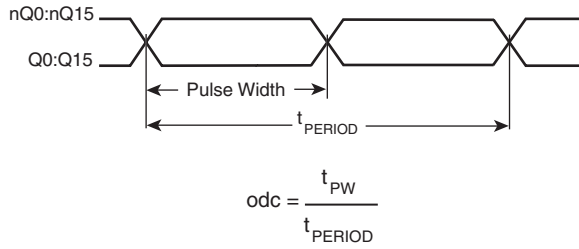
OUTPUT DUTY CYCLE/PULSE WIDTH PERIOD
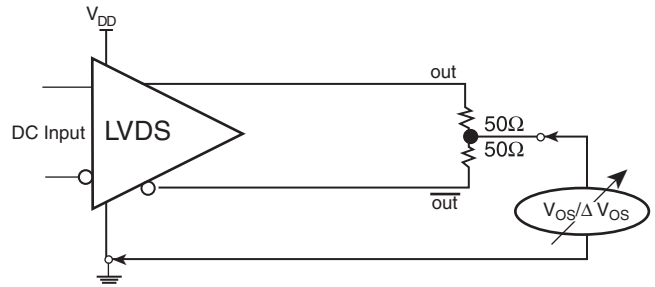
OFFSET VOLTAGE
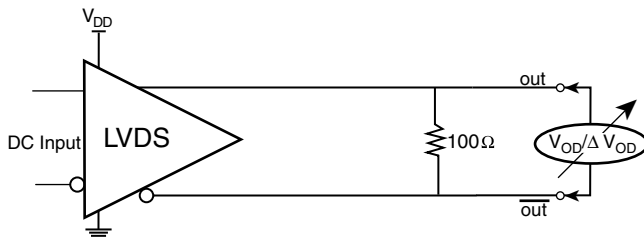
DIFFERENTIAL OUTPUT VOLTAGE
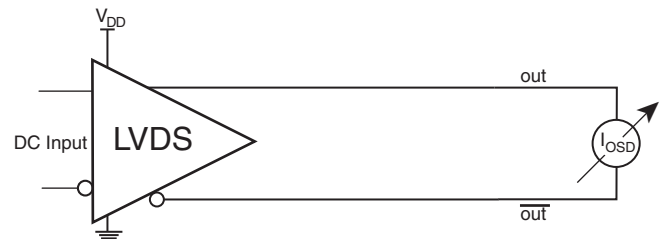
DIFFERENTIAL OUTPUT SHORT CIRCUIT CURRENT
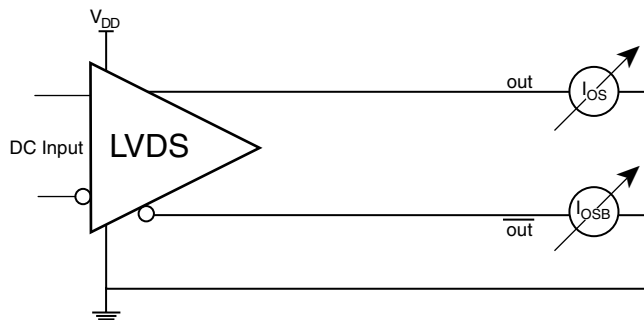
OUTPUT SHORT CIRCUIT CURRENT

POWER OFF LEAKAGE

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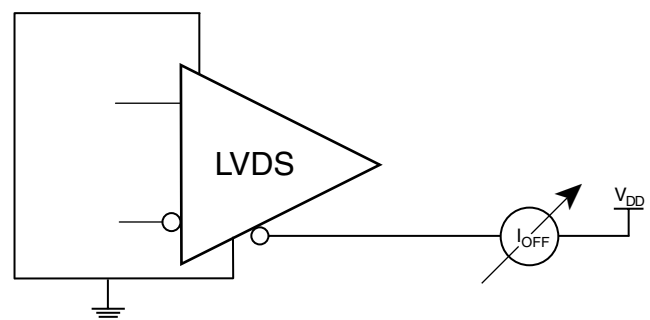
APPLICATION INFORMATION

WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage $V\_REF = V_{DD}/2$ is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to position the V_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and V_{DD}= 3.3V, V_REF should be 1.25V and R2/R1 = 0.609.

FIGURE 1. SINGLE ENDED SIGNAL DRIVING DIFFERENTIAL INPUT
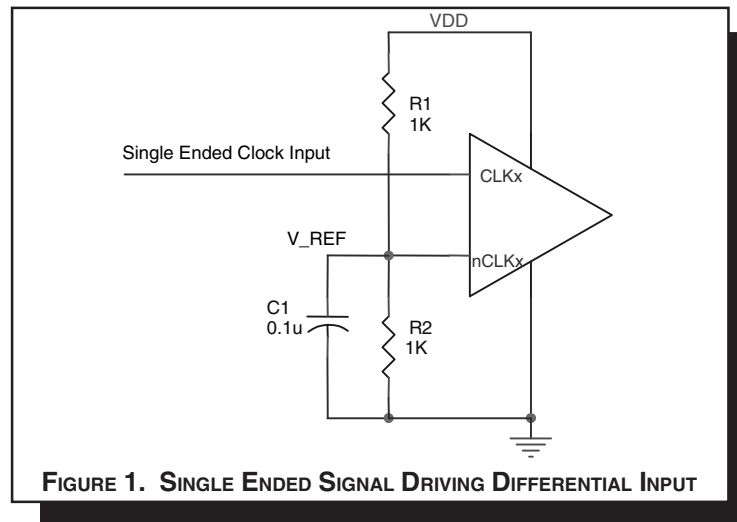
LVDS DRIVER TERMINATION

A general LVDS interface is shown in *Figure 2.* In a 100Ω differential transmission line environment, LVDS drivers require a matched load termination of 100Ω across near the receiver input. For a multiple LVDS outputs buffer, if only partial outputs are used, it is recommended to terminate the un-used outputs.

FIGURE 2. TYPICAL LVDS DRIVER TERMINATION

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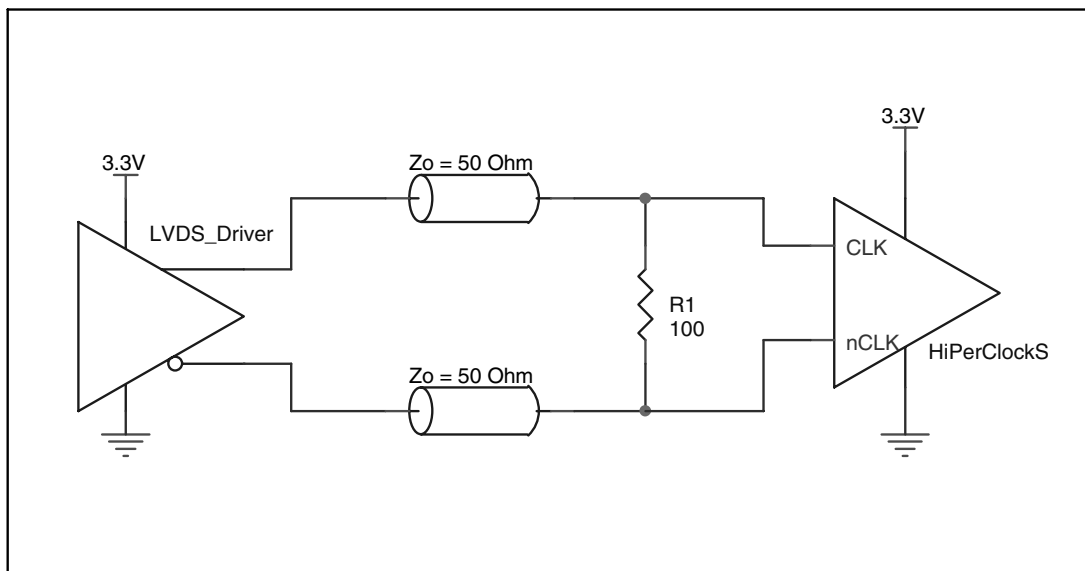
DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. Figures 3A to 3E show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces sug-gested here are examples only. Please consult with the vendor of the driver component to confirm the driver termination re-quirements. For example in *Figure 3A,* the input termination applies for ICS HiPerClockS LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.
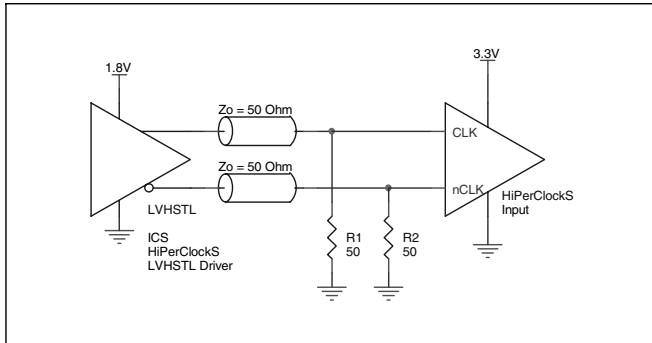
FIGURE 3A. **HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY ICS HIPERCLOCKS LVHSTL DRIVER**
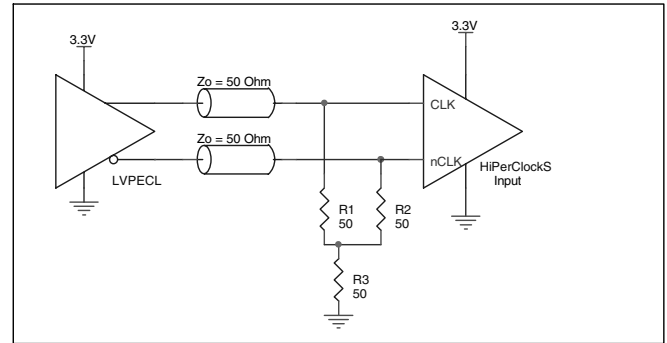
FIGURE 3B. **HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER**
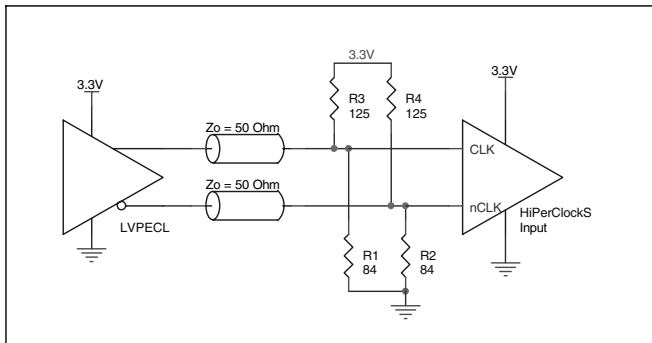
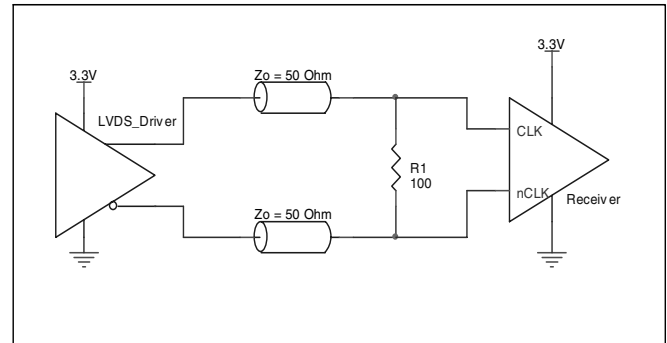**FIGURE 3C.** **HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER**

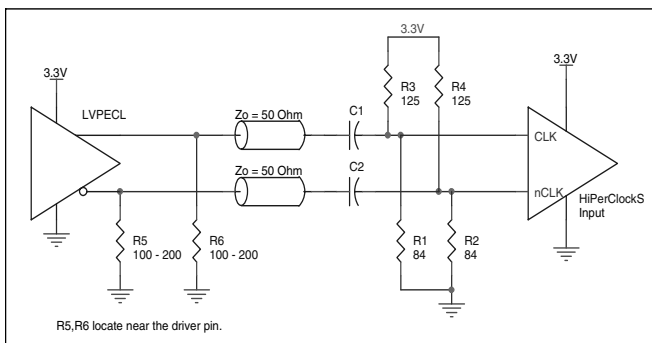**FIGURE 3D.** **HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVDS DRIVER**

FIGURE 3E. **HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER WITH AC COUPLE**

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SCHEMATIC EXAMPLE

Figure 4 shows a schematic example of ICS8516I. In this example, the input is driven by an LVDS driver. For LVDS buffer, it is recommended to terminate the unused outputs for better sig-

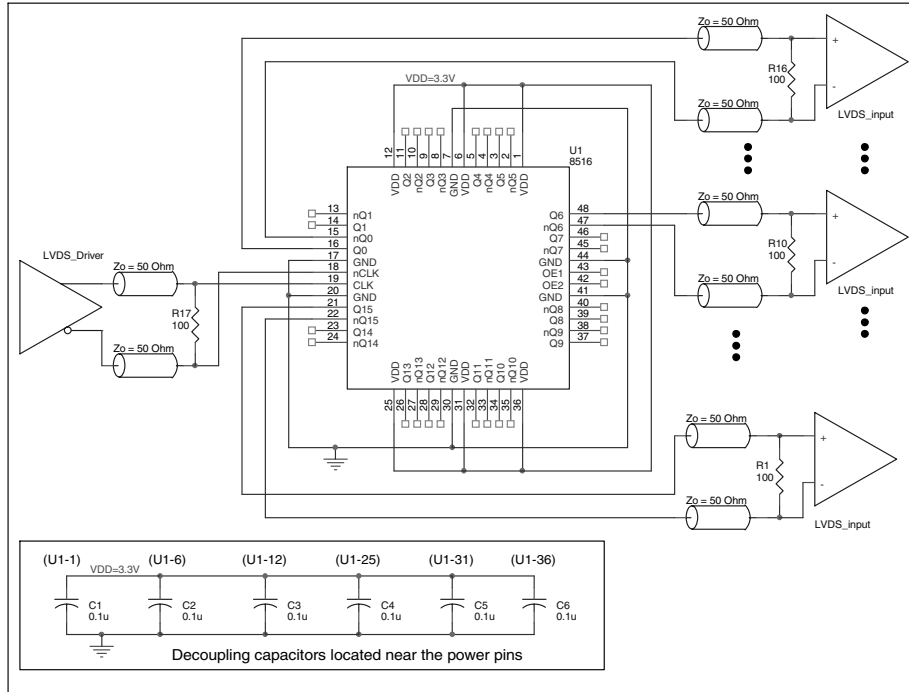nal integrity. The decoupling capacitors should be physically located near the power pin.

FIGURE 4. ICS8516I LVDS BUFFER SCHEMATIC EXAMPLE

RELIABILITY INFORMATION

TABLE 6. θ_{JA} VS. AIR FLOW TABLE FOR 48 LEAD LQFP

θ_{JA} by Velocity (Linear Feet per Minute)			
	0	**200**	**500**
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for ICS8516I is: 1821

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PACKAGE OUTLINE - Y SUFFIX FOR 48 LEAD LQFP
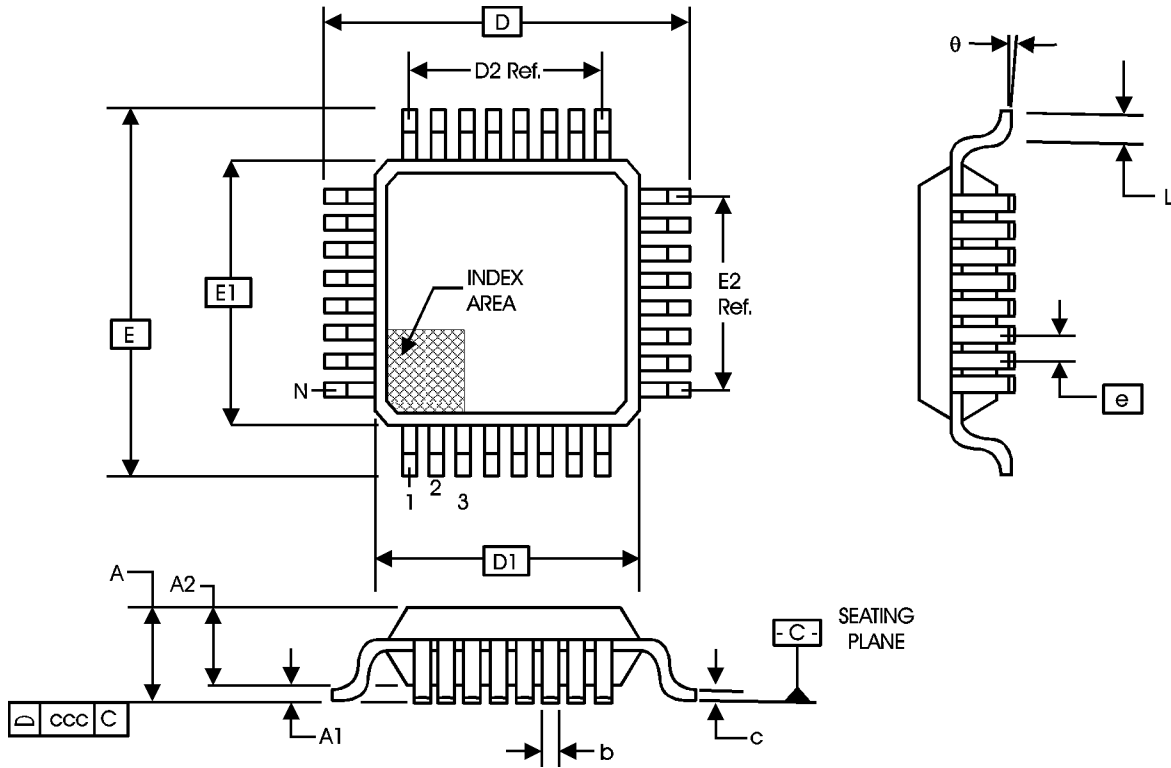
TABLE 7. PACKAGE DIMENSIONS

SYMBOL	JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS		
	BBC		
	MINIMUM	**NOMINAL**	**MAXIMUM**
N	48		
A	--	--	1.60
A1	0.05	--	0.15
A2	1.35	1.40	1.45
b	0.17	0.22	0.27
c	0.09	--	0.20
D	9.00 BASIC		
D1	7.00 BASIC		
D2	5.50 Ref.		
E	9.00 BASIC		
E1	7.00 BASIC		
E2	5.50 Ref.		
e	0.50 BASIC		
L	0.45	0.60	0.75
θ	0°	--	7°
ccc	--	--	0.08

Reference Document: JEDEC Publication 95, MS-026

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TABLE 8. ORDERING INFORMATION

Part/Order Number	Marking	Package	Count	Temperature
ICS8516FYI	ICS8516FYI	48 Lead LQFP	250 per tray	-40°C to 85°C
ICS8516FYIT	ICS8516FYI	48 Lead LQFP on Tape and Reel	1000	-40°C to 85°C
ICS8516FYILF	ICS8516FYILF	48 Lead "Lead-Free" LQFP	250 per tray	-40°C to 85°C
ICS8516FYILFT	ICS8516FYILF	48 Lead "Lead-Free" LQFP on Tape and Reel	1000	-40°C to 85°C

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| \multicolumn{6}{c}{**REVISION HISTORY SHEET**} |
Rev	**Table**	**Page**	**Description of Change**	**Date**
A	T8	12	Ordering Information Table - added Lead-Free part numbers.	7/30/04